



BSI Standards Publication

Test methods for electrical materials, printed boards and other interconnection structures and assemblies

Part 2-801: Thermal conductivity test for base materials

National foreword

This British Standard is the UK implementation of EN IEC 61189-2-801:2023. It is identical to IEC 61189-2-801:2023. It supersedes BS IEC 61189-2-801:2023, which is withdrawn.

The UK participation in its preparation was entrusted to Technical Committee EPL/501, Electronic Assembly Technology.

A list of organizations represented on this committee can be obtained on request to its committee manager.

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English Version

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conductivity test for base materials
(IEC 61189-2-801:2023)

Méthodes d'essai pour les matériaux électriques, les cartes
imprimées et autres structures d'interconnexion et
ensembles - Partie 2-801: Essai de conductivité thermique
pour matériaux de base
(IEC 61189-2-801:2023)

Prüfverfahren für Elektromaterialien, Leiterplatten und
andere Verbindungsstrukturen und Baugruppen - Teil 2-
801: Prüfung der thermischen Leitfähigkeit für
Grundwerkstoffe
(IEC 61189-2-801:2023)

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European Committee for Electrotechnical Standardization
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European foreword

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The following dates are fixed:

- latest date by which the document has to be implemented at national (dop) 2024-05-30 level by publication of an identical national standard or by endorsement
- latest date by which the national standards conflicting with the (dow) 2026-08-30 document have to be withdrawn

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The text of the International Standard IEC 61189-2-801:2023 was approved by CENELEC as a European Standard without any modification.

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